

EXPRESS MAIL NO. EL896635910US

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: William T. CHEN,) RE: PRELIMINARY AMENDMENT
et al.)
Serial No.: Not yet assigned) Group: Not yet assigned
Filed: Concurrently herewith) Examiner: Not yet assigned
For: "METHOD OF FORMING) Our Ref: B-4361 619261-9
SELECTIVE ELECTROLESS PLATING)
ON POLYMER SURFACES") Date: December 18, 2001

Commissioner of Patents and Trademarks
Box New Patent Application
Washington, D.C., 20231

Sir:

Prior to examination of the above-identified application, it is respectfully requested that the following amendments be made to the Claims:

IN THE CLAIMS

Please replace original Claims 4-6, 9, 11, 14-15, and 17 with amended Claims 4-6, 9, 11, 14-15, and 17, which are set forth below. (Appendix A, which is enclosed herewith, shows how original Claims 4-6, 9, 11, 14-15, and 17 were amended to produce amended Claims 4-6, 9, 11, 14-15, and 17.)

4. (Amended) A method according to claim 1, wherein the substrate material is an aromatic polymer and the strippable coating comprises a non-aromatic polymer.

5. (Amended) A method according to claim 1, comprising using the same laser to ablate the strippable coating and to activate the

substrate surface, and reducing the power of the laser for the activation of the substrate surface.

6. (Amended) A method according to claim 1, comprising depositing further metal on the electrolessly plated region of the substrate.

9. (Amended) A method according to claim 1, comprising ablating the substrate material underlying the ablated area of the strippable coating to form a recess in the substrate material before activating the polymer surface.

11. (Amended) A method according to claim 1, comprising using the laser to ablate the strippable coating, selectively activate the substrate surface and drill a landless via in the substrate material in the same step.

14. (Amended) A method according to claim 1, comprising selectively plating non-planar features on the substrate surface.

15. (Amended) A method according to claim 1, comprising forming an integrated resistor by selectively activating and plating a region between two circuit interconnects on the substrate surface.

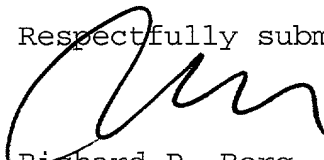
17. (Amended) A method according to claim 1 used to re-map a wafer.

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REMARKS

This Preliminary Amendment amends Claims 4-6, 9, 11, 14-15, and 17 so that these claims are no longer multiply dependent in order to reduce the official fees due in connection with this application. The Applicants may elect to amend Claims 4-6, 9, 11, 14-15, and 17 to make these claims again multiply dependent, or to add additional claims to this application to provide coverage similar to, broader than, or narrower than the present claims at any time during the pendency of the above-identified U.S. application.

Respectfully submitted,



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Enclosure: Appendix A (2 pages)

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Appendix A

(VERSION WITH MARKINGS TO SHOW CHANGES MADE)

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Please amend the Claims as follows:

4. (Amended) A method according to [any one of claims 1 to 3]claim 1, wherein the substrate material is an aromatic polymer and the strippable coating comprises a non-aromatic polymer.
5. (Amended) A method according to [any preceding claim]claim 1, comprising using the same laser to ablate the strippable coating and to activate the substrate surface, and reducing the power of the laser for the activation of the substrate surface.
6. (Amended) A method according to [any preceding claim]claim 1, comprising depositing further metal on the electrolessly plated region of the substrate.
9. (Amended) A method according to [any preceding claim]claim 1, comprising ablating the substrate material underlying the ablated area of the strippable coating to form a recess in the substrate material before activating the polymer surface.
11. (Amended) A method according to [any preceding claim]claim 1, comprising using the laser to ablate the strippable coating, selectively activate the substrate surface and drill a landless via in the substrate material in the same step.
14. (Amended) A method according to [any preceding claim]claim 1, comprising selectively plating non-planar features on the substrate surface.

Appendix A

(VERSION WITH MARKINGS TO SHOW CHANGES MADE)

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15. (Amended) A method according to [any preceding claim]claim 1, comprising forming an integrated resistor by selectively activating and plating a region between two circuit interconnects on the substrate surface.

17. (Amended) A method according to [any preceding claim]claim 1 used to re-map a wafer.

15. (Amended) A method according to [any preceding claim]claim 1, comprising forming an integrated resistor by selectively activating and plating a region between two circuit interconnects on the substrate surface.